



Material Content Data Sheet



Sales Product Name		BTS3050EJ		Issued		23. January 2018		
MA#		MA001469596						
Package		PG-TDSO-8-31		Weight*		67.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.461	2.17	2.17	21666	21666
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		563	
	non noble metal	iron	7439-89-6	0.760	1.13		11264	
wire	non noble metal	copper	7440-50-8	30.851	45.74	46.94	457380	469348
	non noble metal	copper	7440-50-8	0.322	0.48	0.48	4778	4778
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.14		1428
plastics		epoxy resin	-	3.757	5.57		55700	
	inorganic material	silicondioxide	60676-86-0	28.258	41.89	47.60	418942	476070
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7372	7372
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12228	12228
glue	plastics	epoxy resin	-	0.101	0.15		1494	
	noble metal	silver	7440-22-4	0.475	0.70	0.85	7044	8538
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com